

ABSTRACT OF THE DISCLOSURE

A chuck system for supporting a semiconductor wafer that includes a chuck platform for supporting the semiconductor wafer, and a lift structure movably coupled with the chuck platform to receive the semiconductor wafer that includes a lift base, and at least one lift pin removably coupled with the lift base, the lift pin having two ends with a first end removably coupled to the lift base and a second end for supporting the semiconductor wafer during lifting operation of the lift structure.

5

LAW OFFICES

FINNEGAN, HENDERSON,
FARABOW, GARRETT,
& DUNNER, L.L.P.
1300 I STREET, N. W.
WASHINGTON, DC 20005
202-408-4000